

100 →

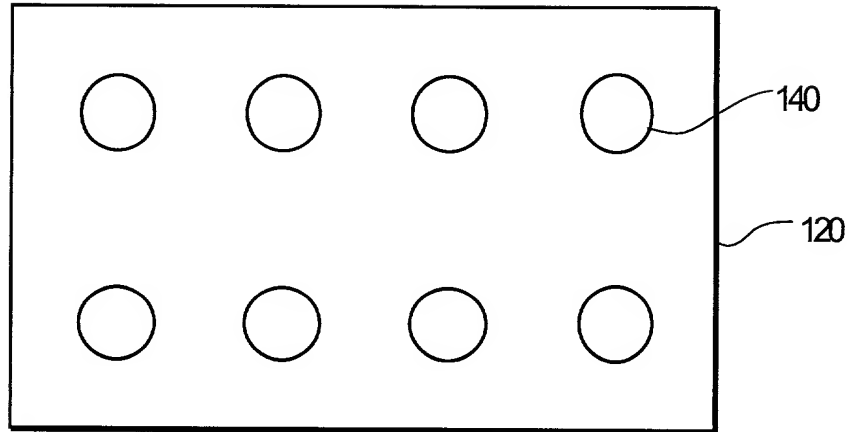


FIG. 1A
(PRIOR ART)

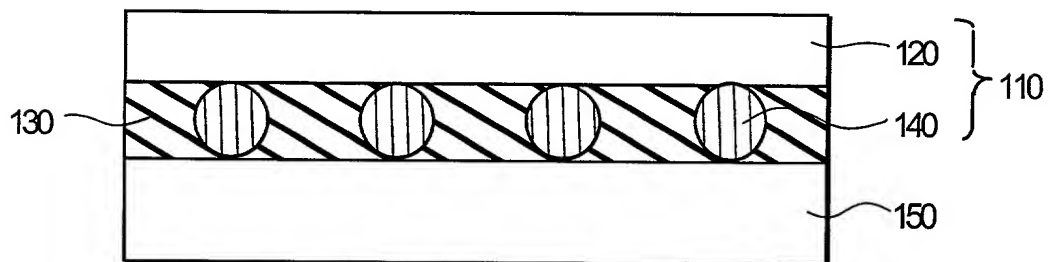


FIG. 1B
(PRIOR ART)

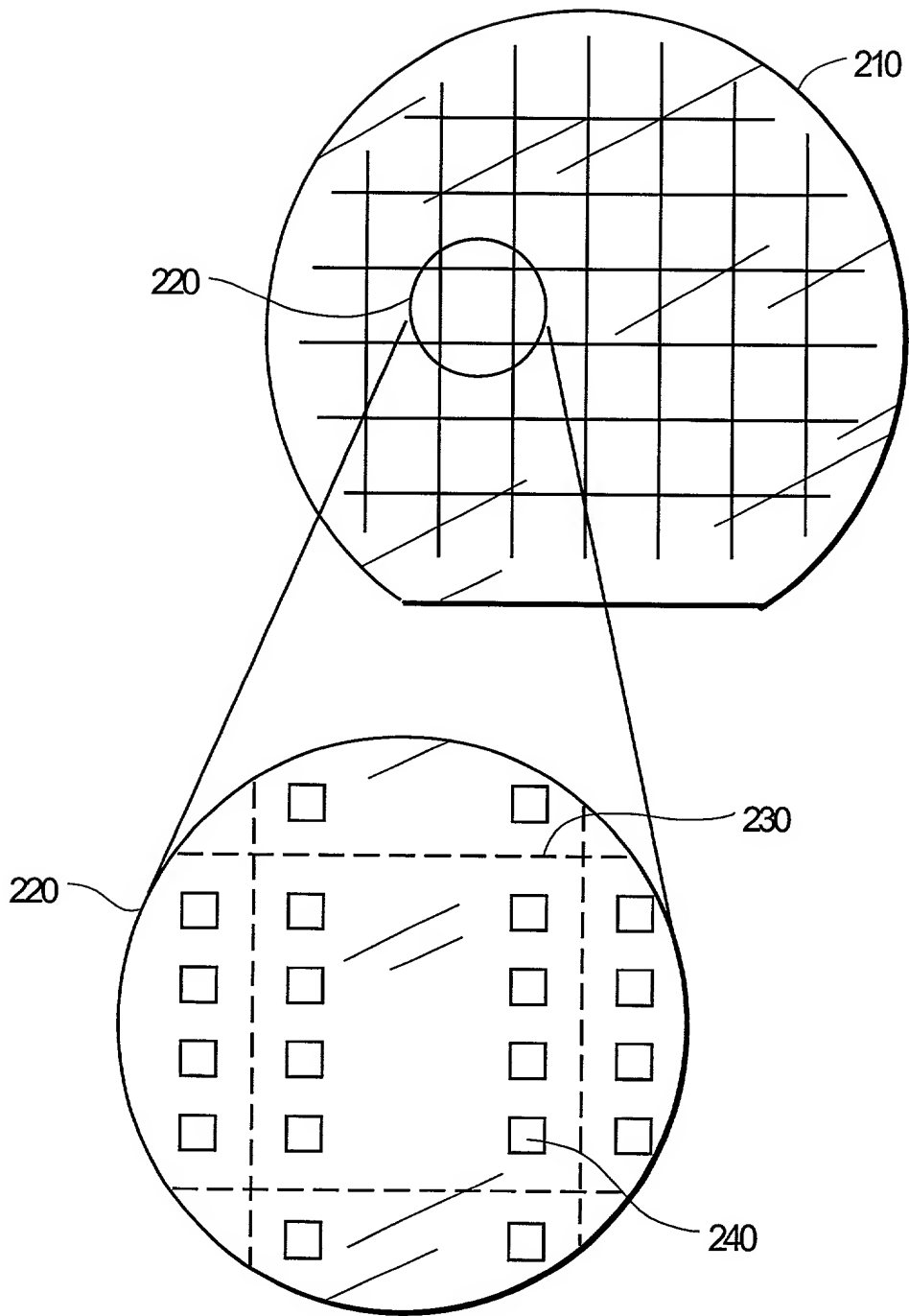


FIG. 2

FIG. 3A is a perspective view of a rectangular frame assembly 310. The assembly includes a plurality of vertical support members 320 and a plurality of horizontal support members 322. The vertical support members 320 are spaced apart and extend vertically. The horizontal support members 322 are spaced apart and extend horizontally. The vertical support members 320 are connected to the horizontal support members 322 at their ends. The assembly 310 is shown in a perspective view, with the front face of the frame assembly 310 facing the viewer. The vertical support members 320 are shown as thin vertical lines, and the horizontal support members 322 are shown as thin horizontal lines. The assembly 310 is shown in a perspective view, with the front face of the frame assembly 310 facing the viewer.

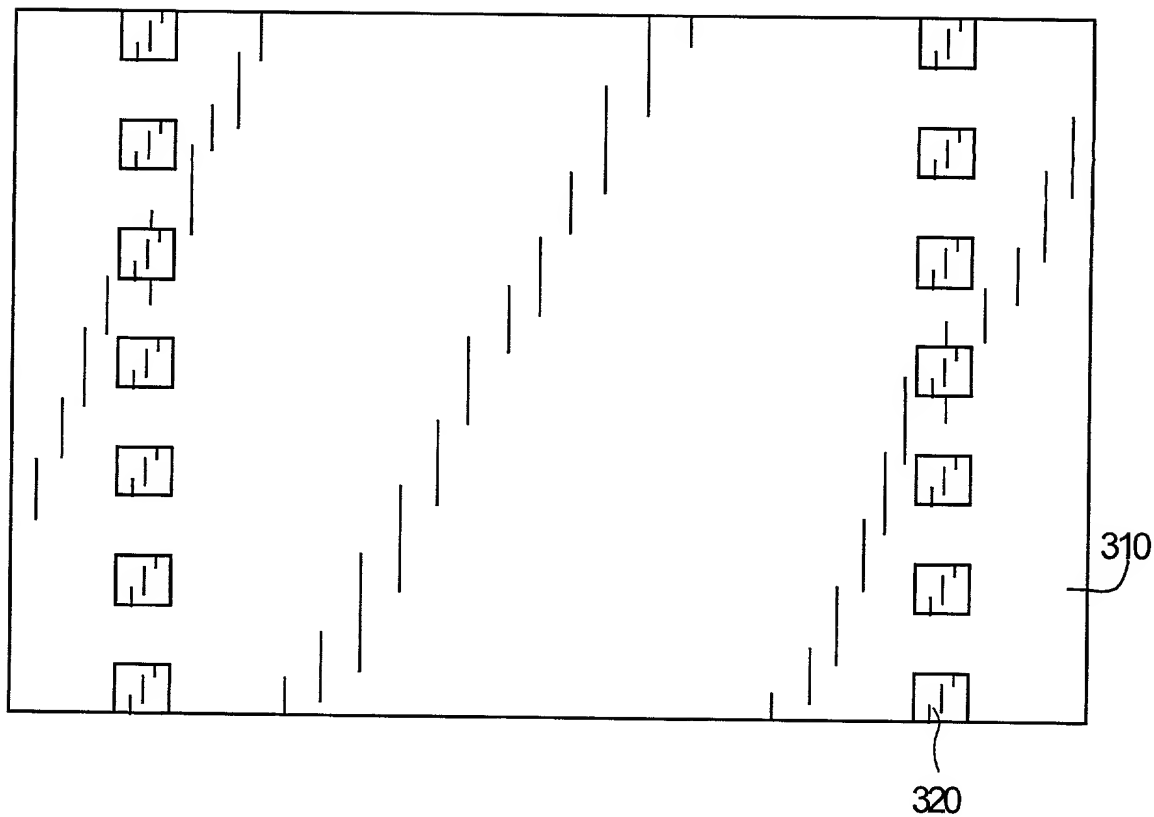


FIG. 3A

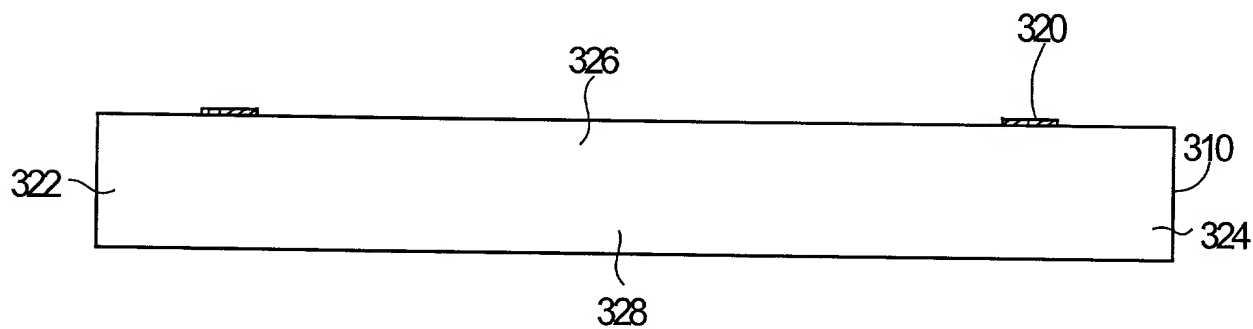


FIG. 3B

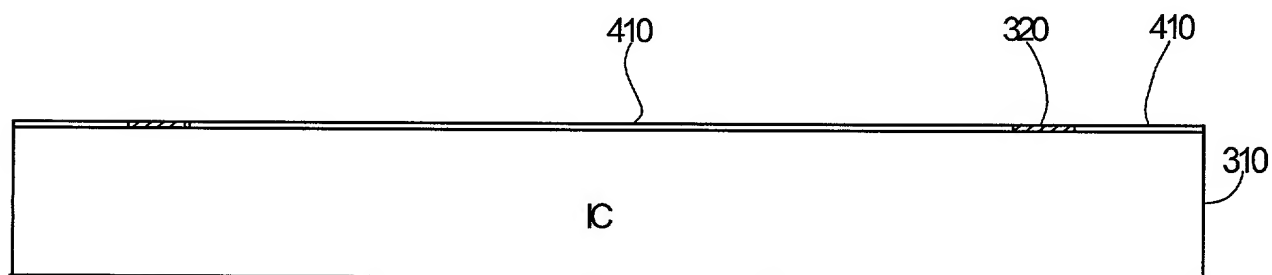
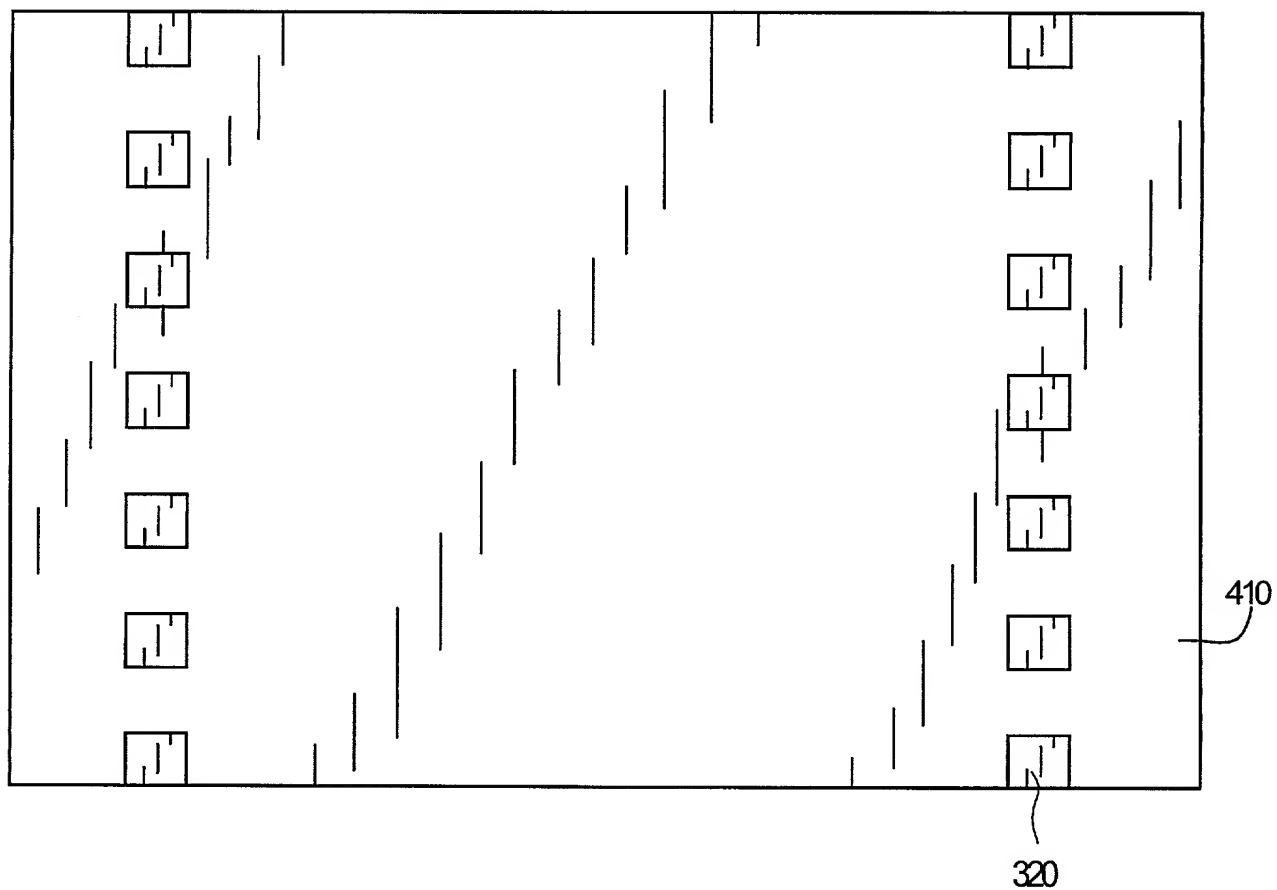


FIG. 5A is a schematic diagram of a device 500 in a first state. The device 500 includes a substrate 510 and a plurality of conductive traces 410. The traces 410 are arranged in a grid pattern on the substrate 510. The device 500 is shown in a perspective view.

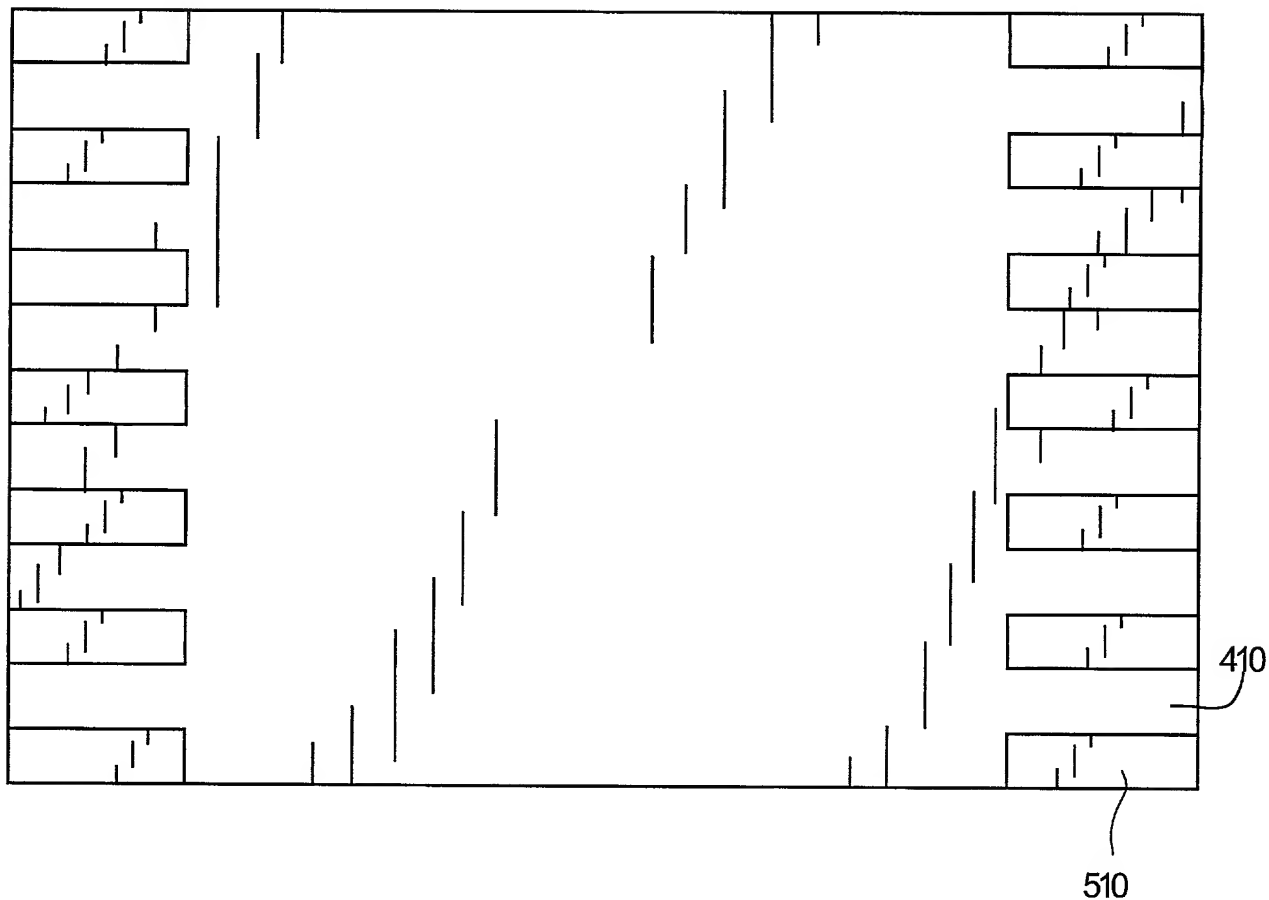


FIG. 5A

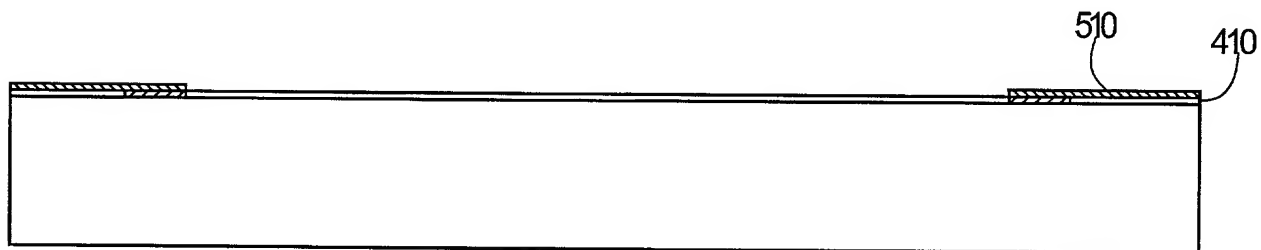


FIG. 5B

FIG. 6A is a schematic diagram of a system 100. The system 100 includes a plurality of components 110, 120, 130, 140, 150, 160, 170, 180, 190, 200, 210, 220, 230, 240, 250, 260, 270, 280, 290, 300, 310, 320, 330, 340, 350, 360, 370, 380, 390, 400, 410, 420, 430, 440, 450, 460, 470, 480, 490, 500, 510, 520, 530, 540, 550, 560, 570, 580, 590, 600, 610, 620, 630, 640, 650, 660, 670, 680, 690, 700, 710, 720, 730, 740, 750, 760, 770, 780, 790, 800, 810, 820, 830, 840, 850, 860, 870, 880, 890, 900, 910, 920, 930, 940, 950, 960, 970, 980, 990.

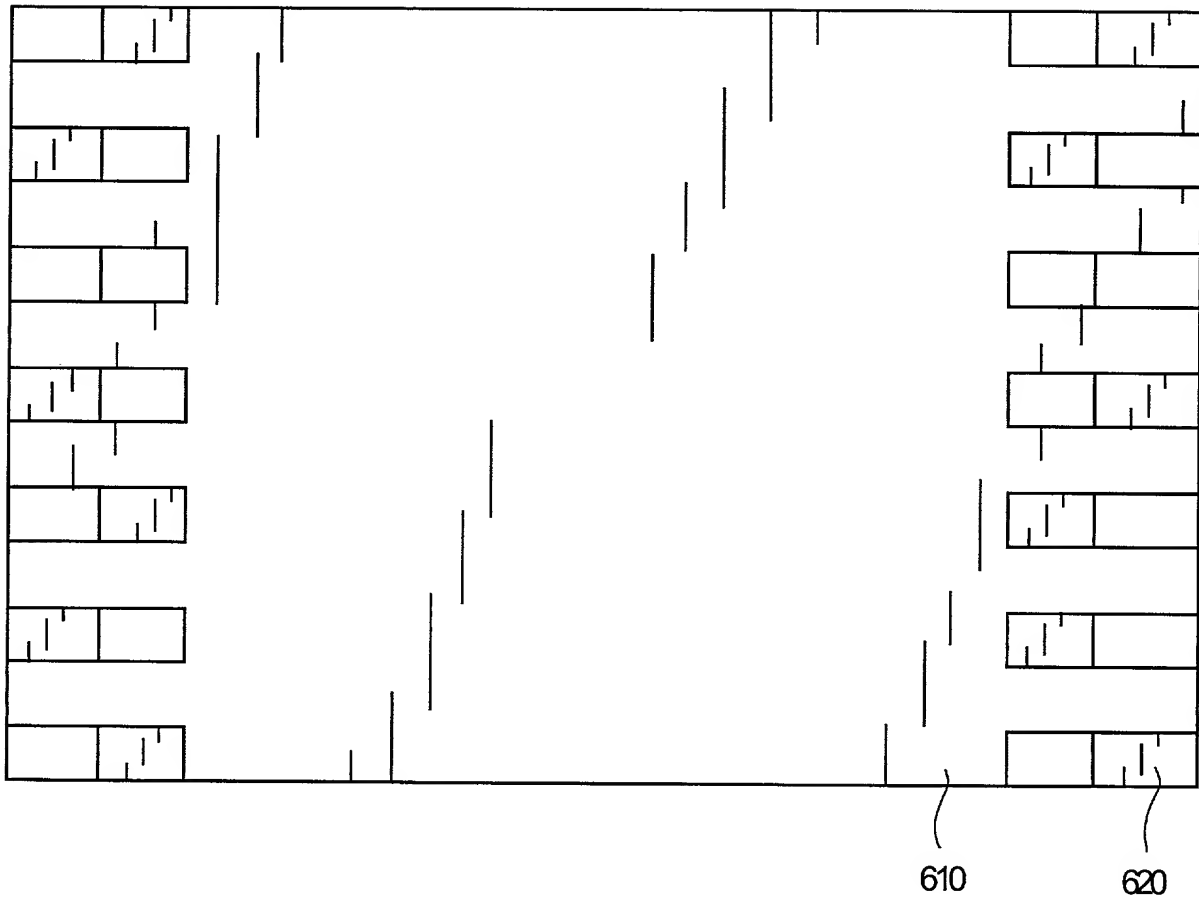


FIG. 6A

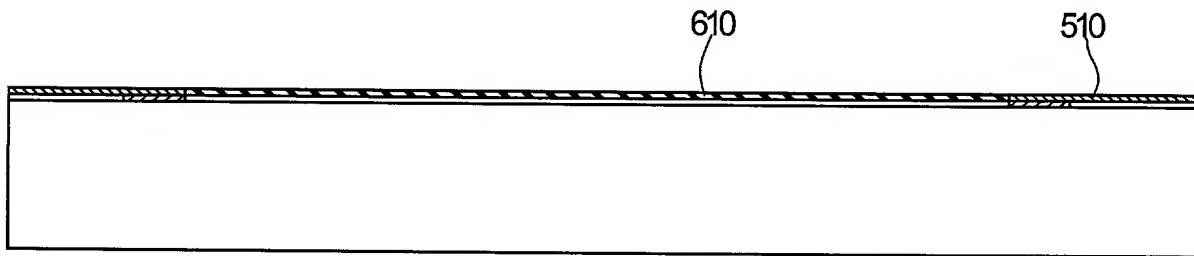
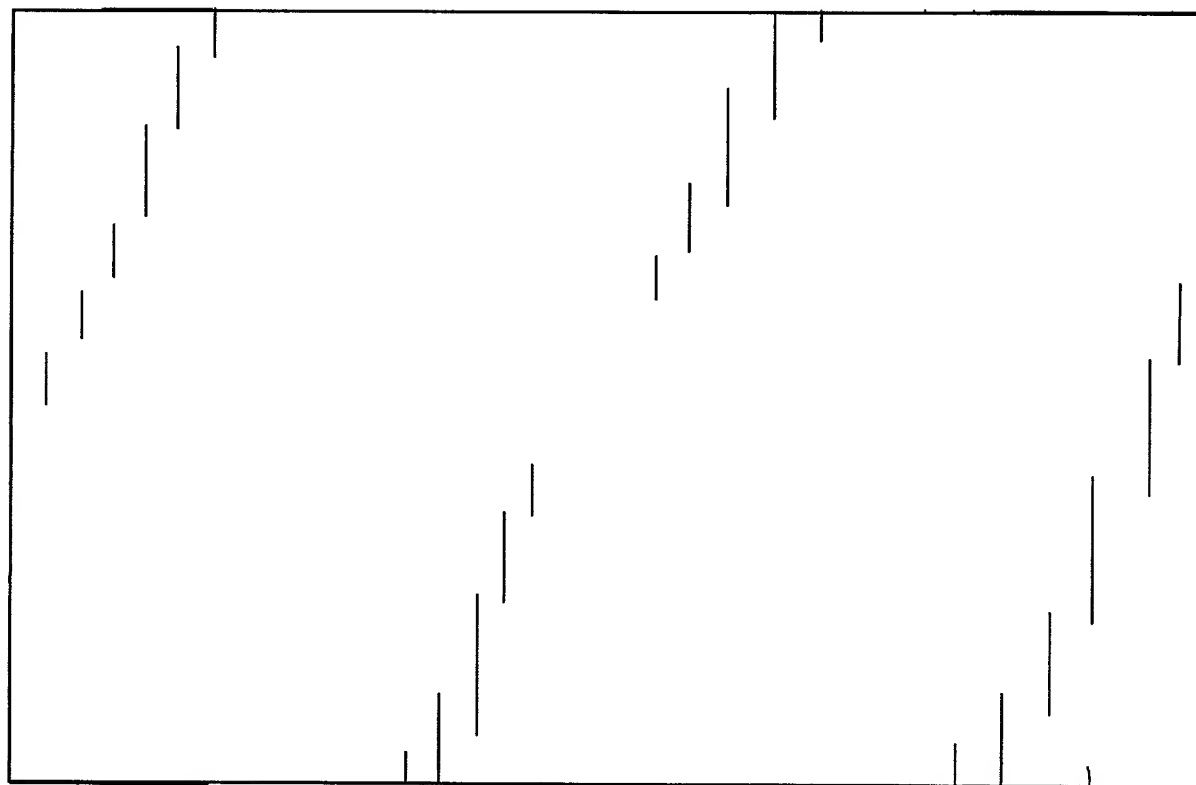


FIG. 6B



710

FIG. 7A

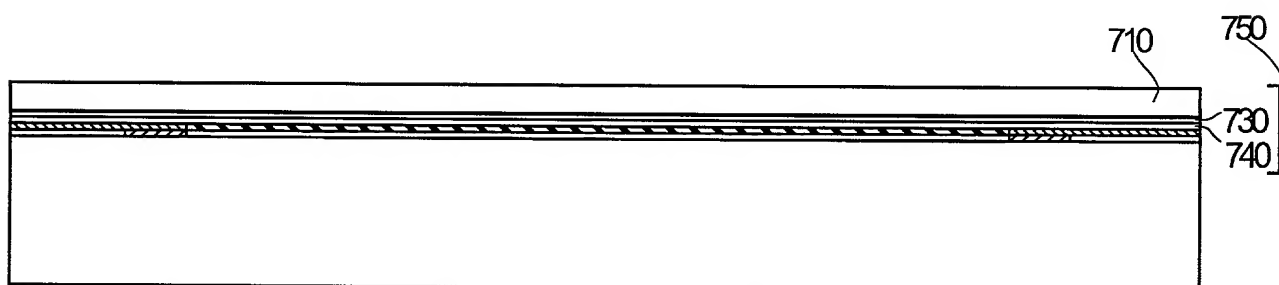
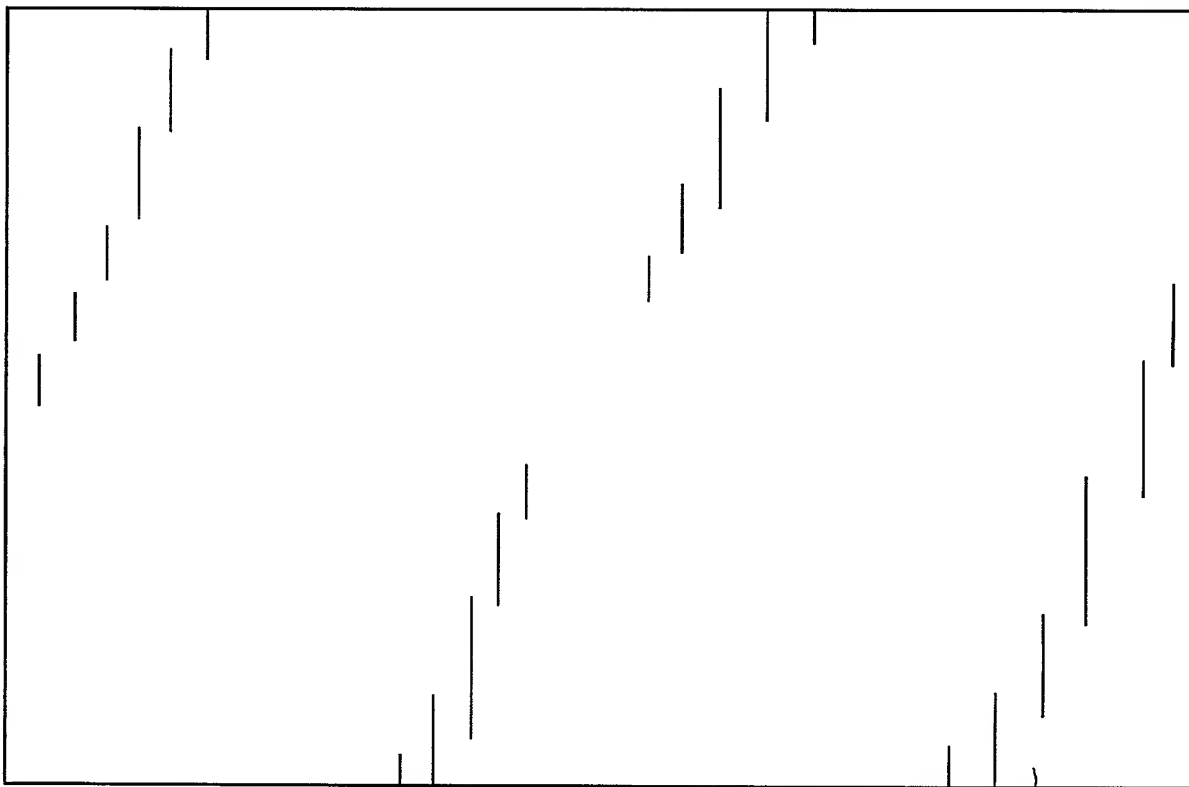
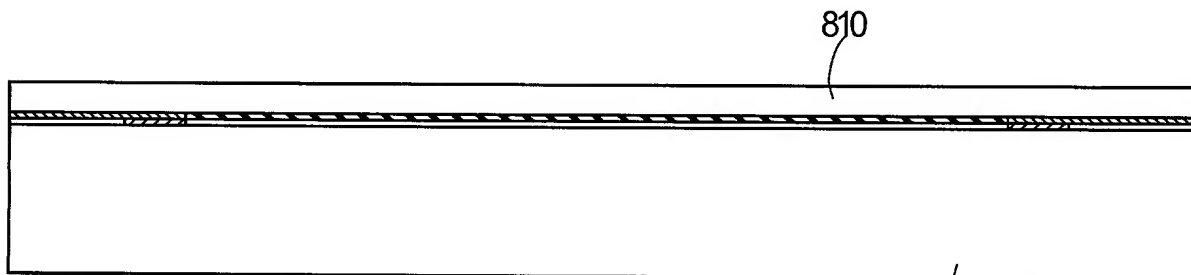


FIG. 7B



810

FIG. 8A



810

310

FIG. 8B

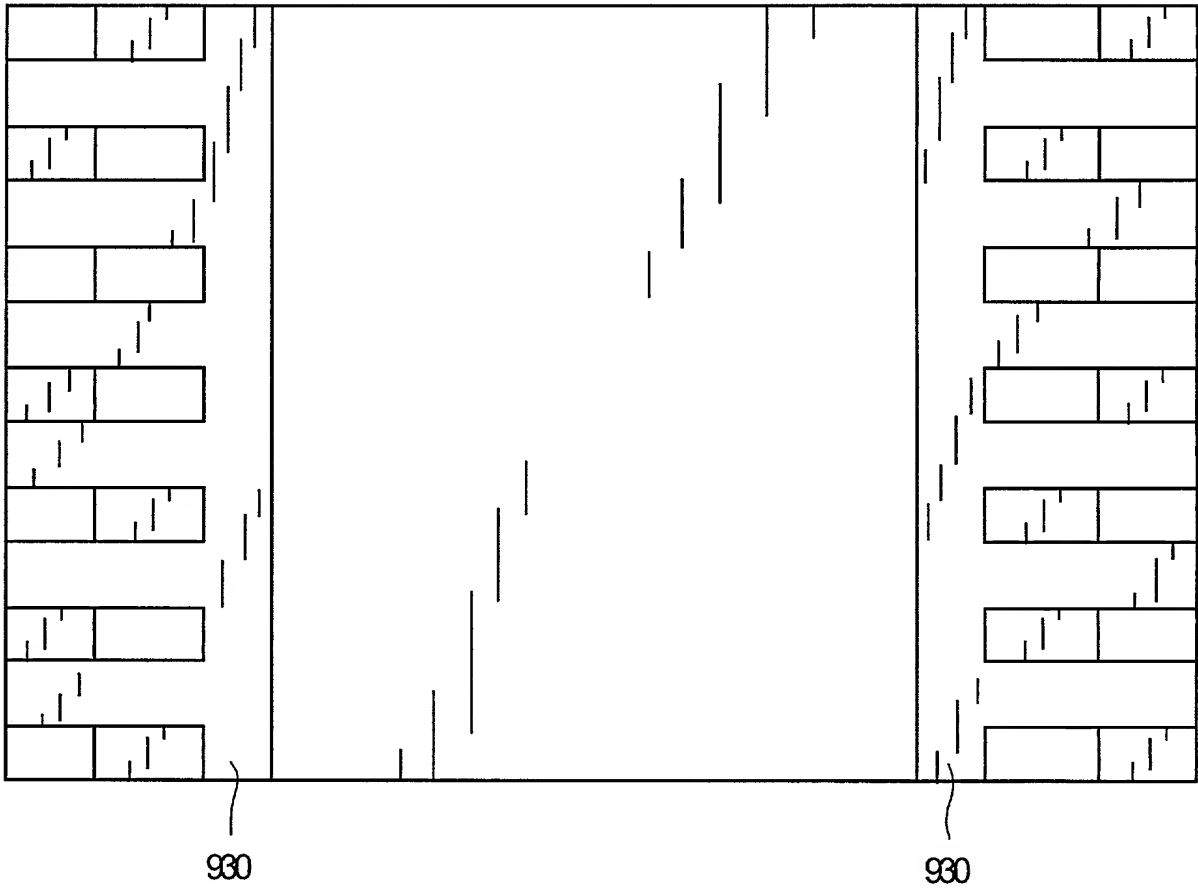


FIG 9A

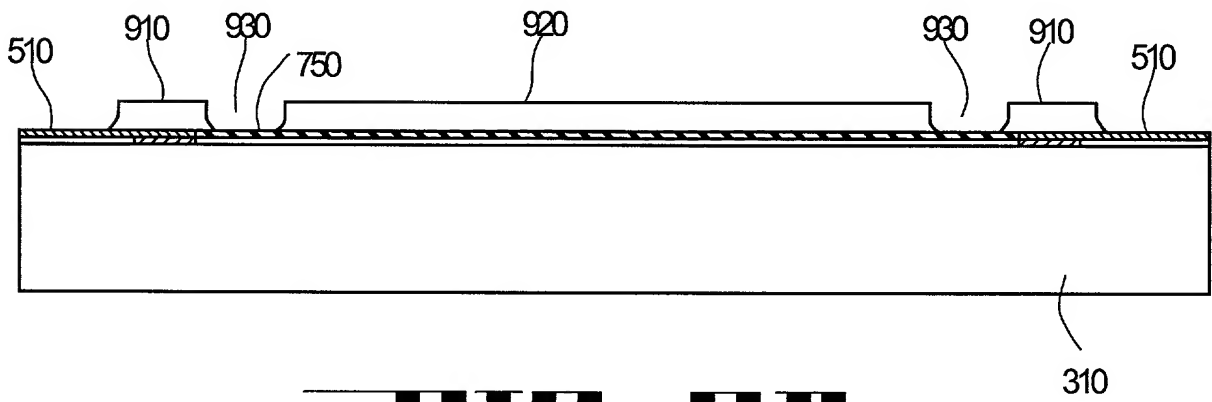


FIG 9B

FIG. 10A is a perspective view of a device 1000 in a first state. The device 1000 includes a base 310 and a plurality of protrusions 910. The protrusions 910 are arranged in a row along the top edge of the base 310. The device 1000 is shown in a perspective view, with the base 310 and the protrusions 910 being clearly visible.

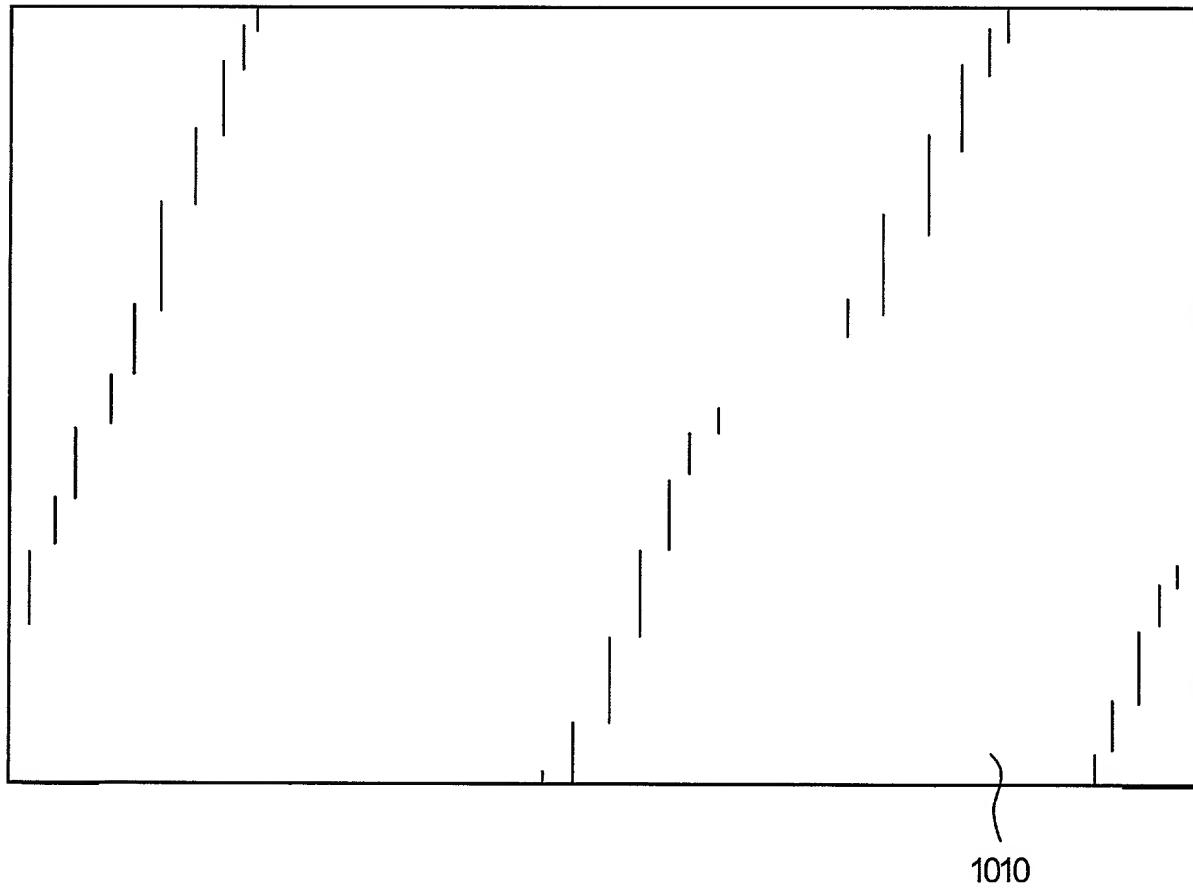


FIG. 10A

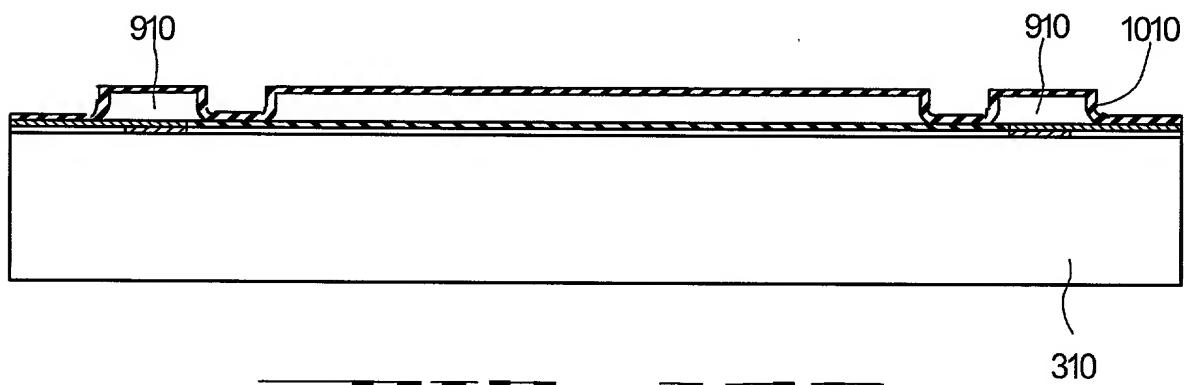


FIG. 10B

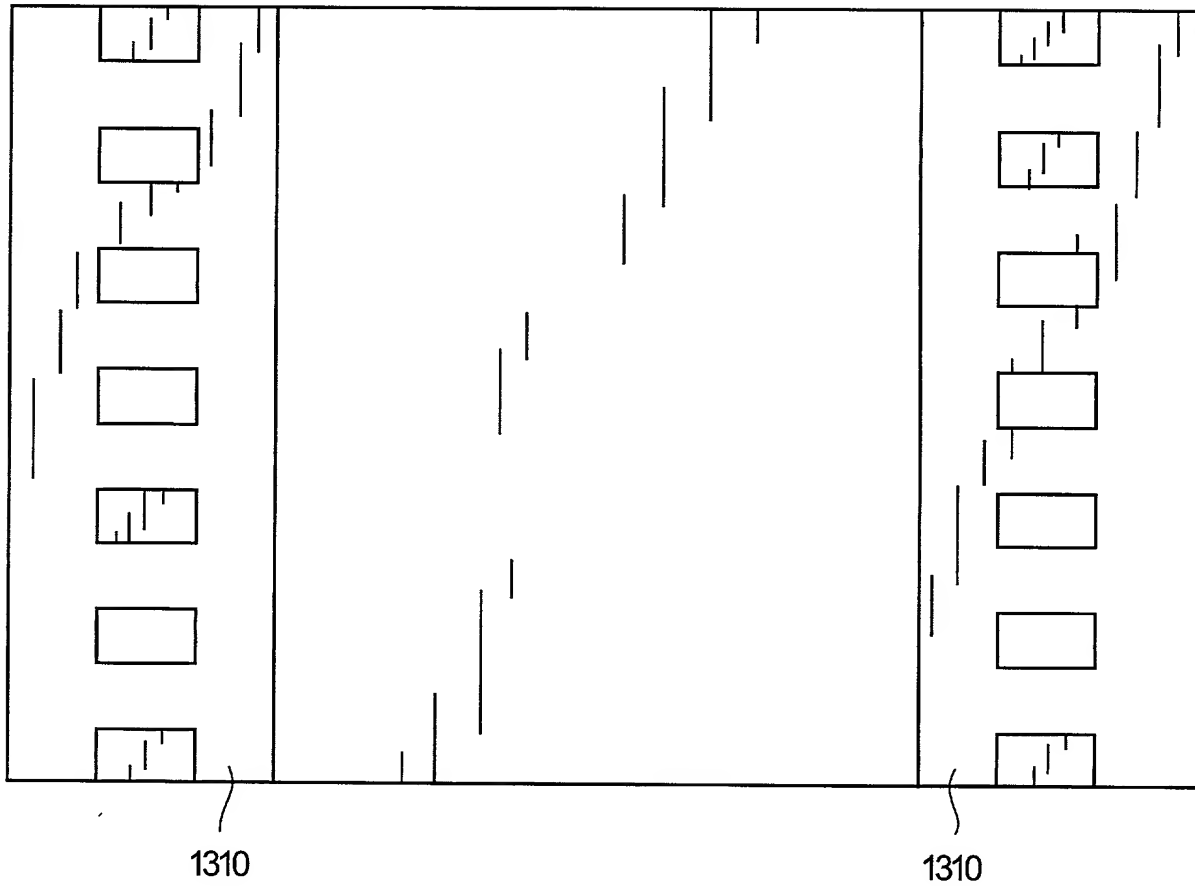


FIG 13A

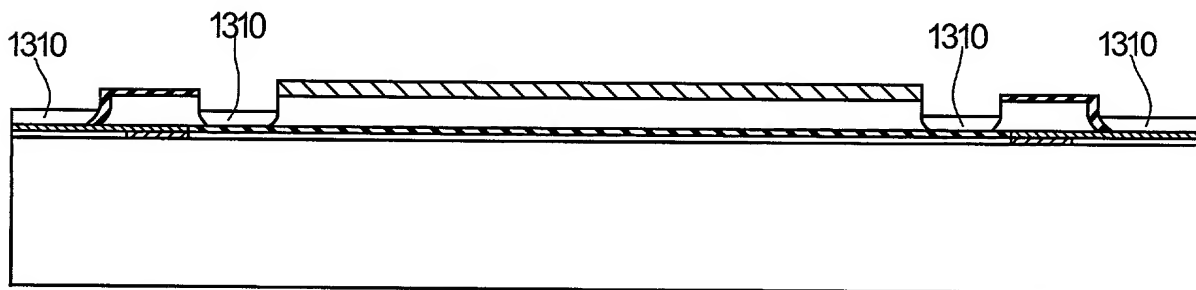


FIG 13B

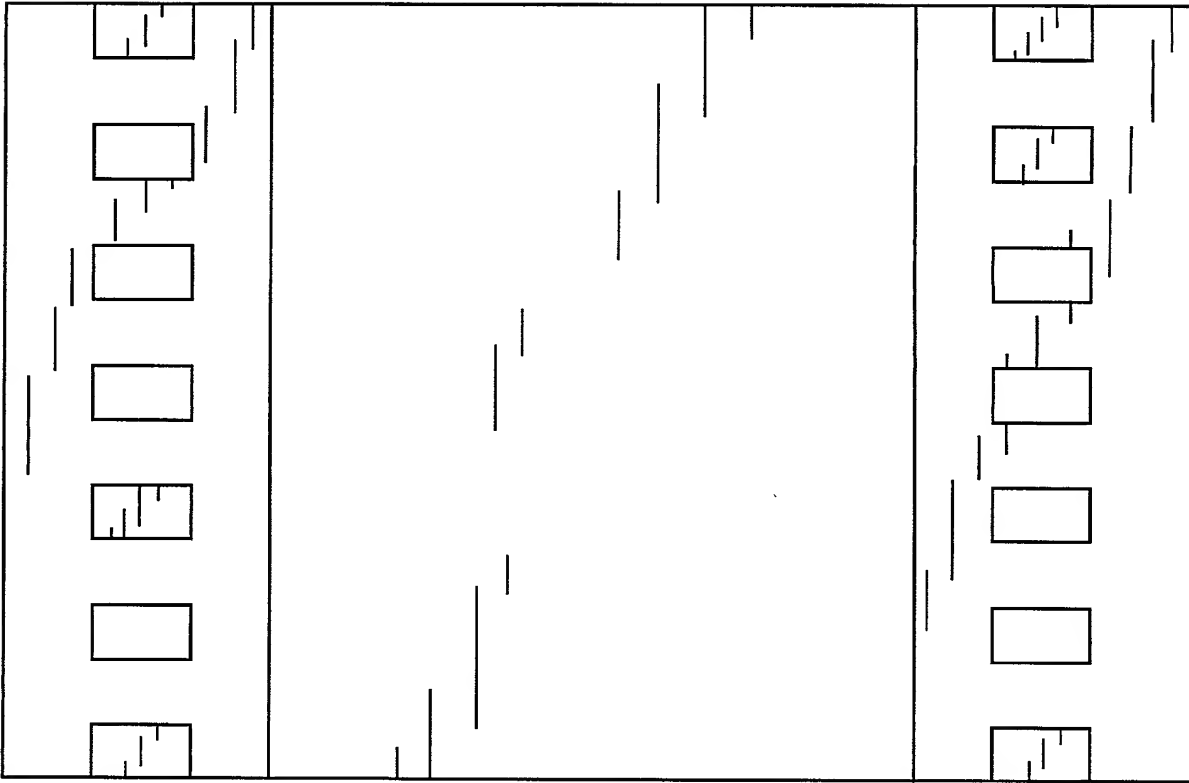
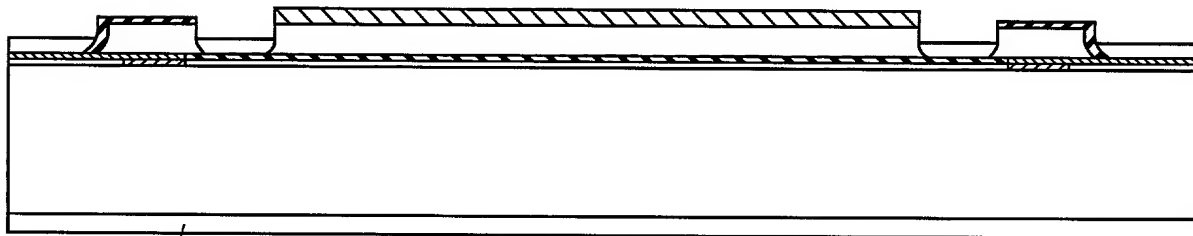


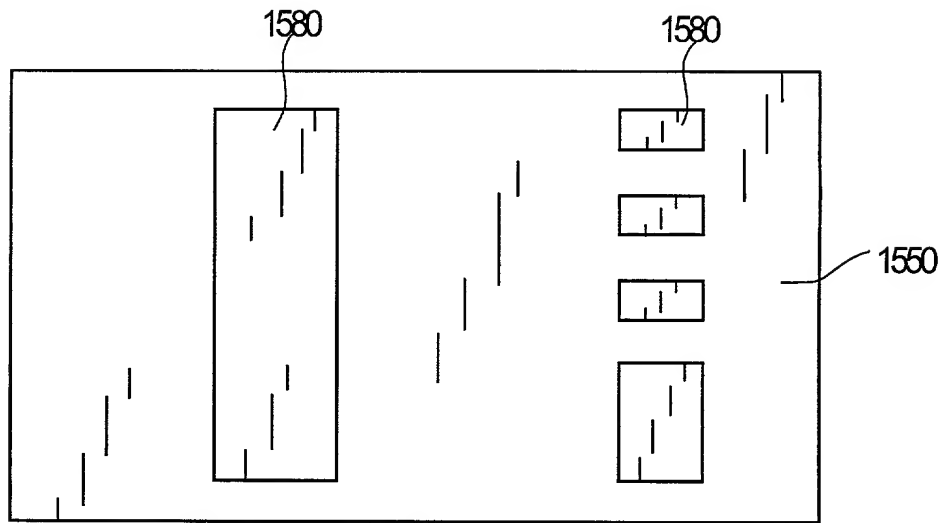
FIG 14A



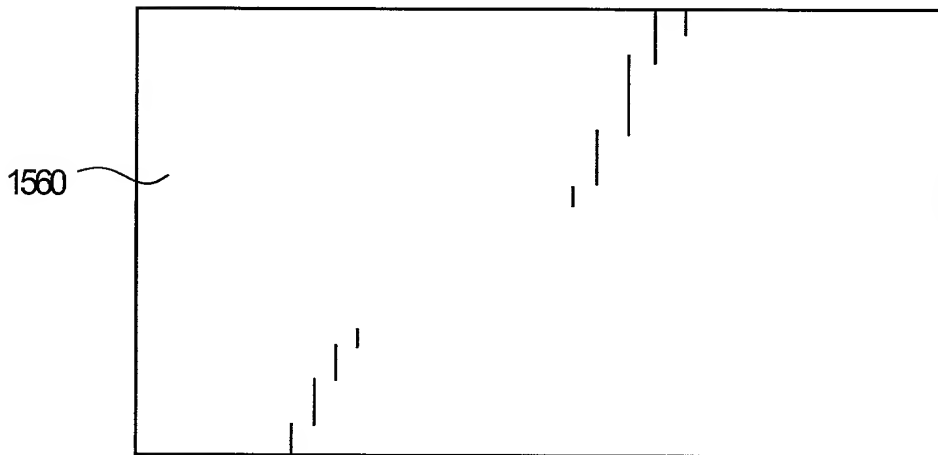
1410

FIG 14B

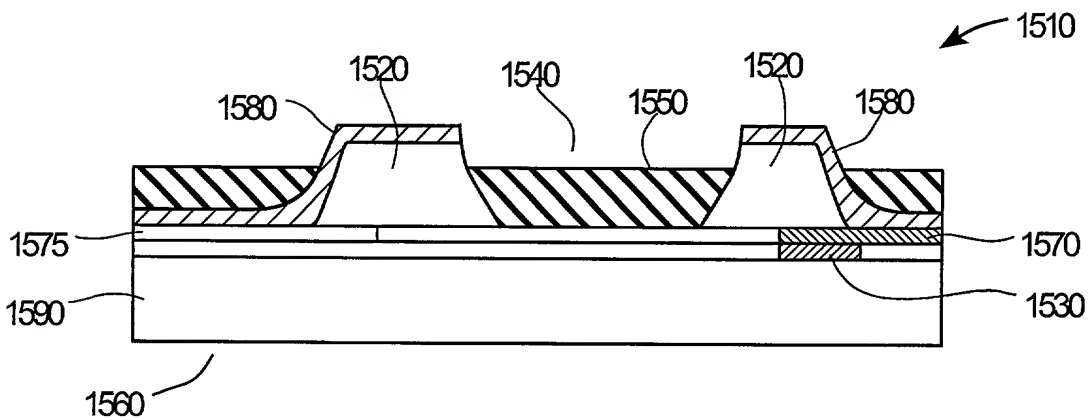
FIG. 15A is a top view of a semiconductor device 1500. The device includes a central rectangular region 1580 and four smaller rectangular regions 1580 arranged in a 2x2 grid on the right side of the device. The device is labeled 1550.



FIG_15A



FIG_15B



FIG_15C

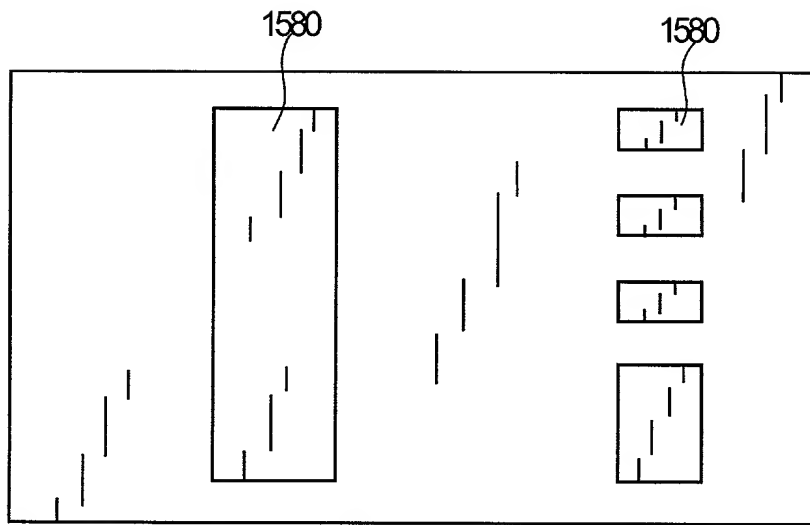


FIG. 16A

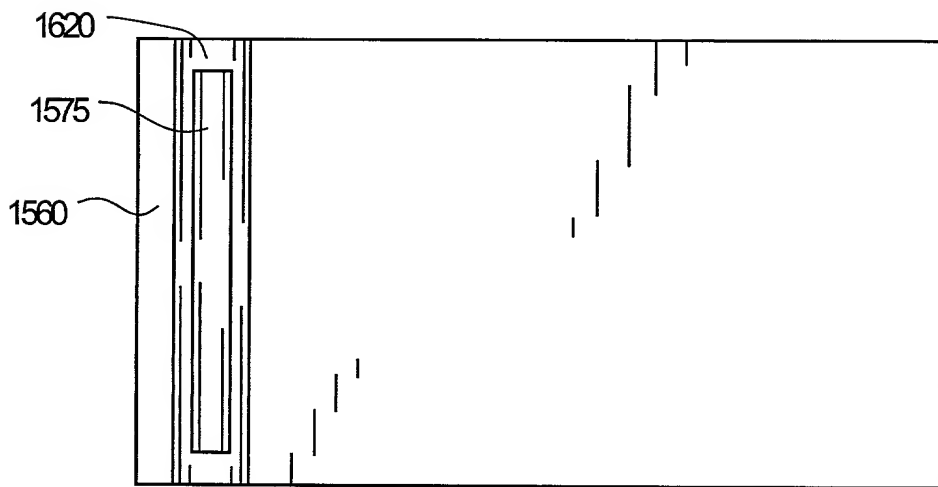


FIG. 16B

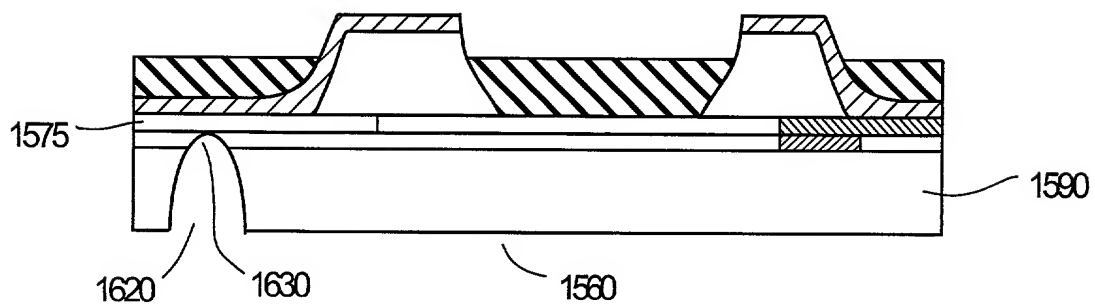


FIG. 16C

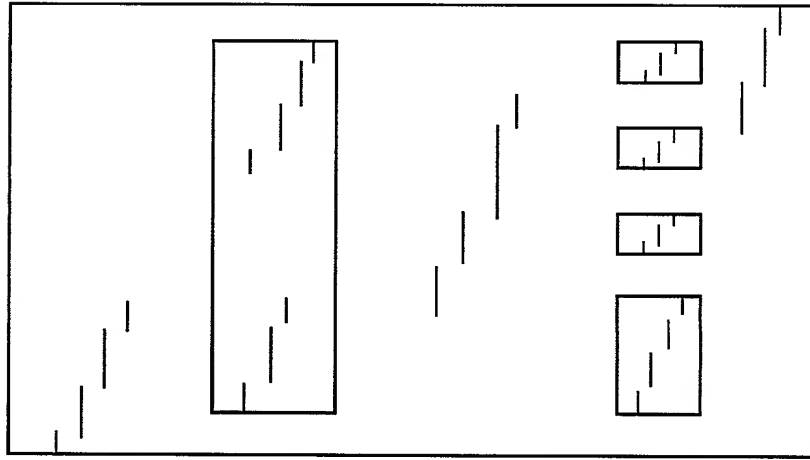


FIG 17A

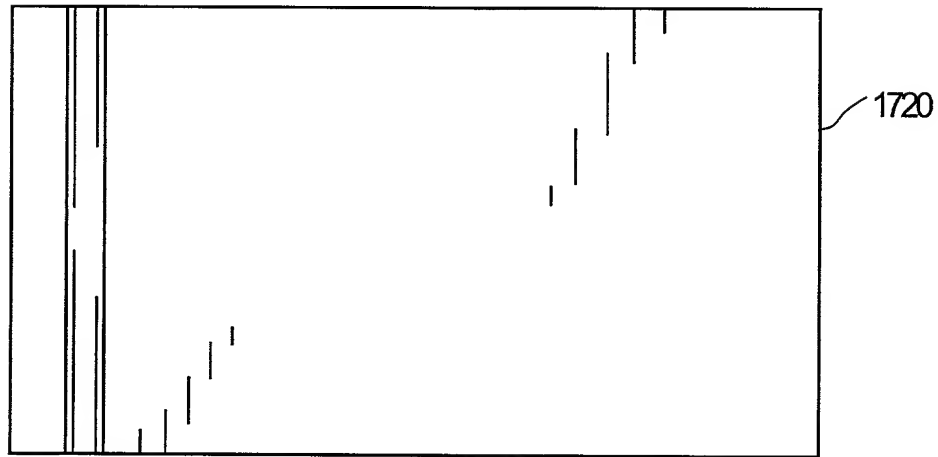


FIG 17B

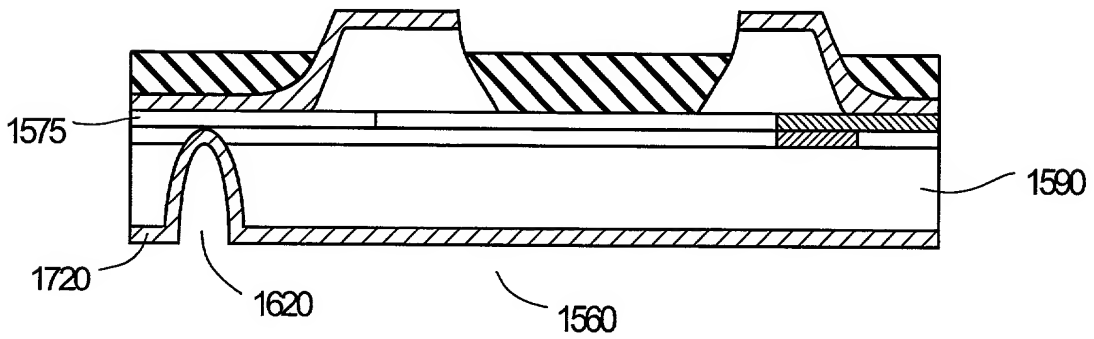


FIG 17C

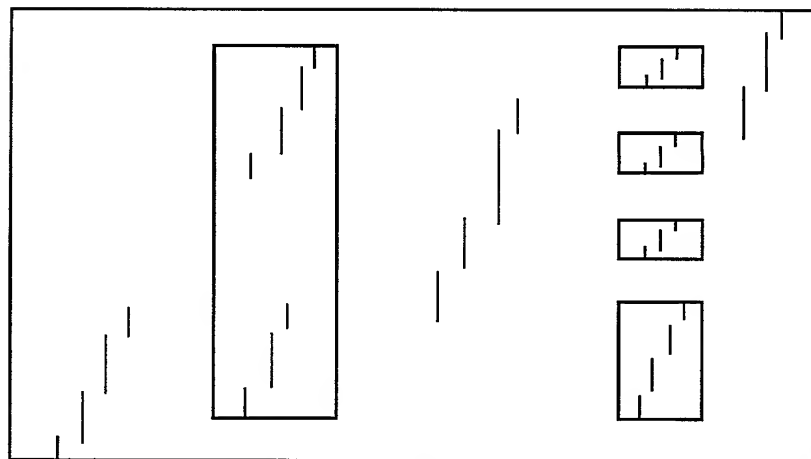


FIG 18A

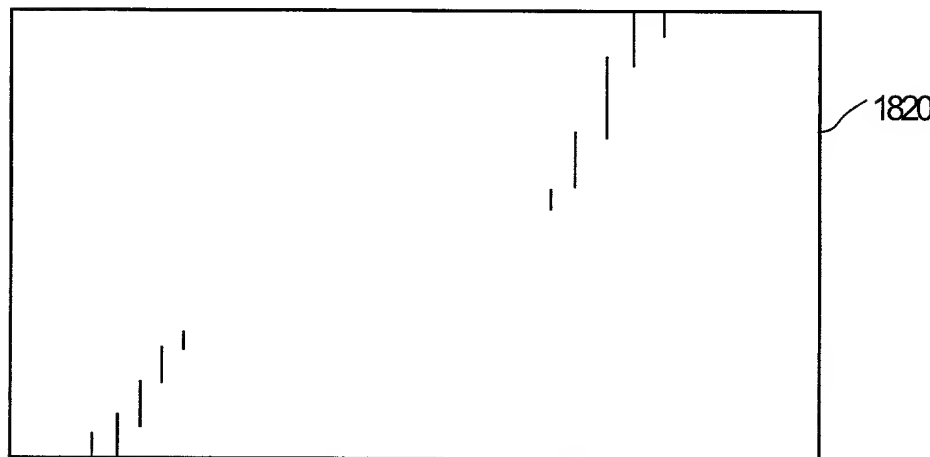


FIG 18B

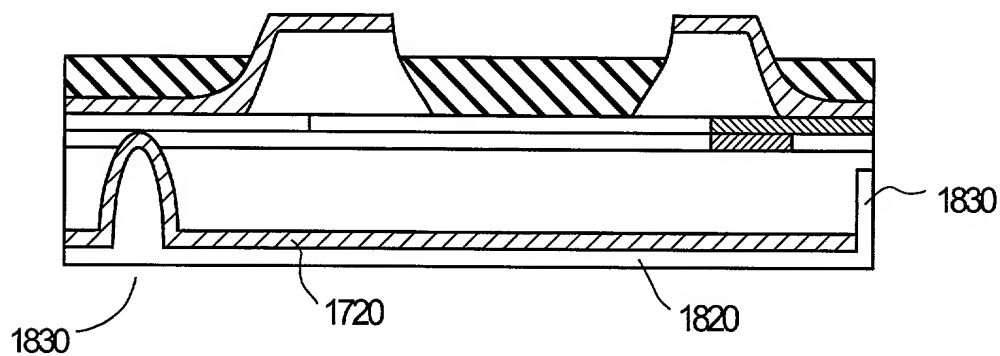


FIG 18C

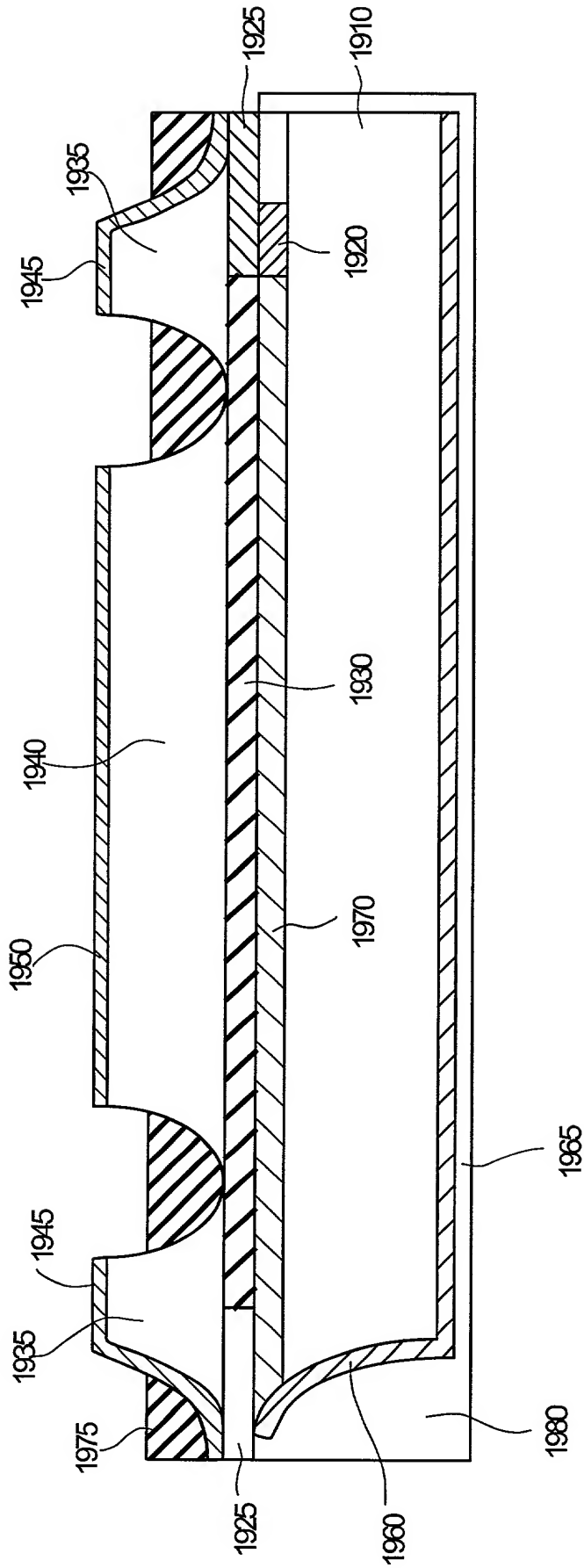


FIG. 19

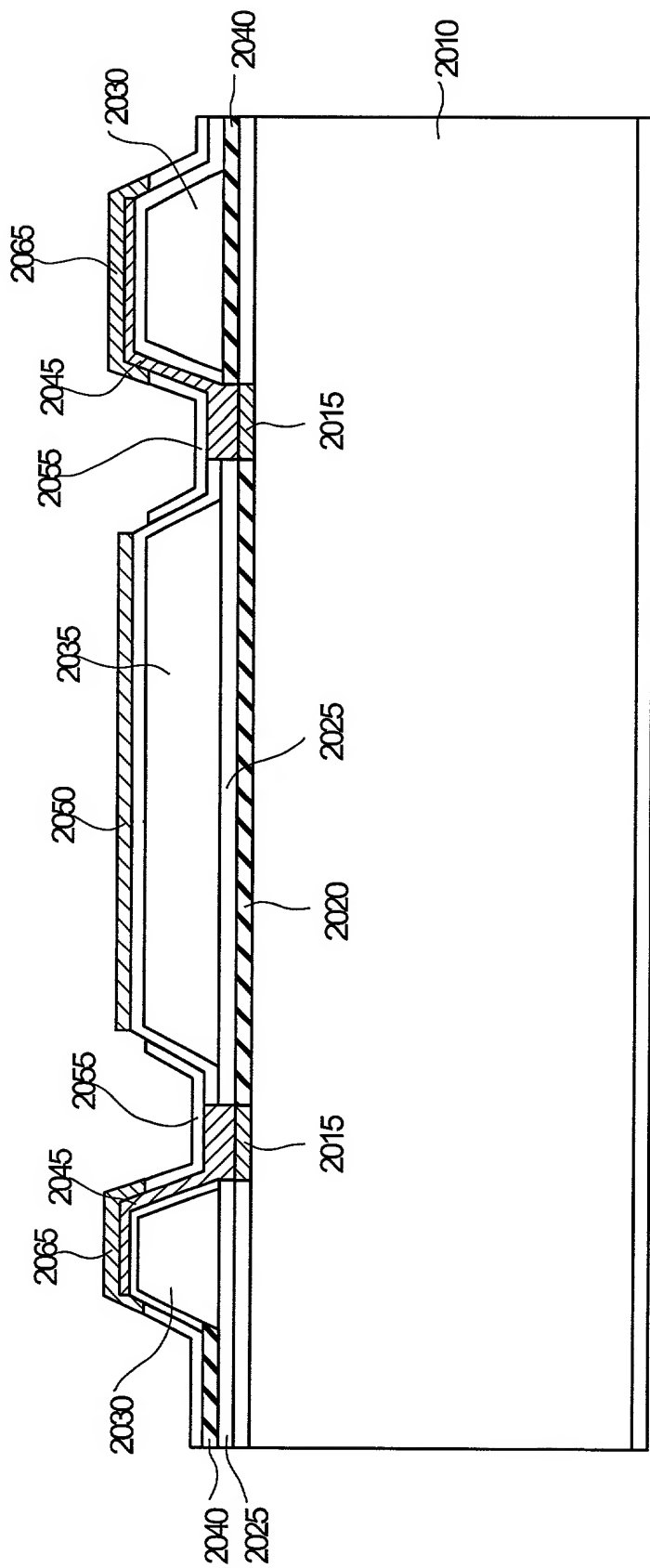
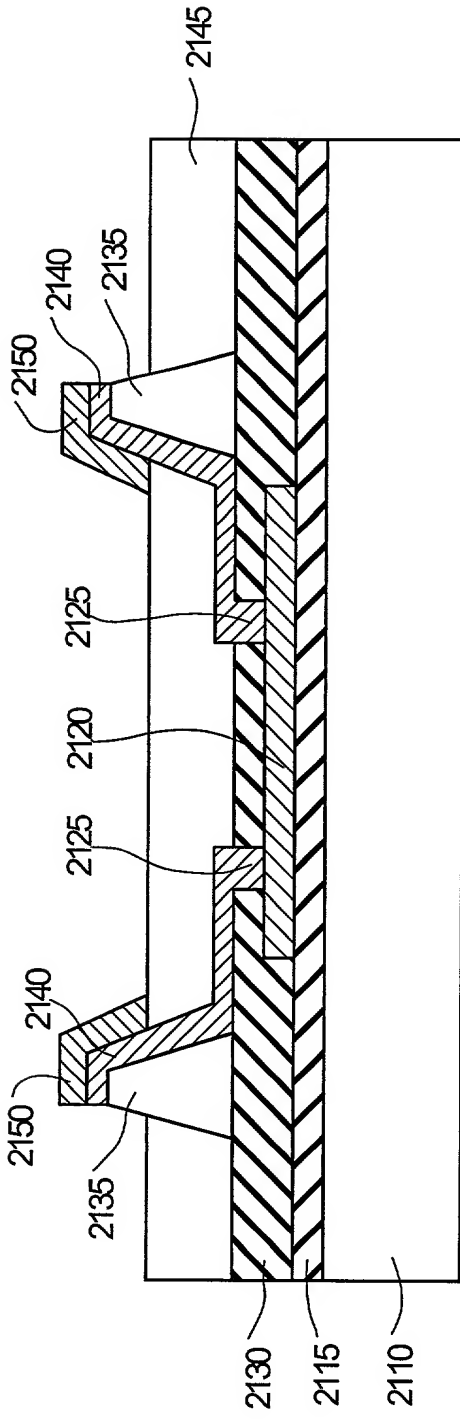
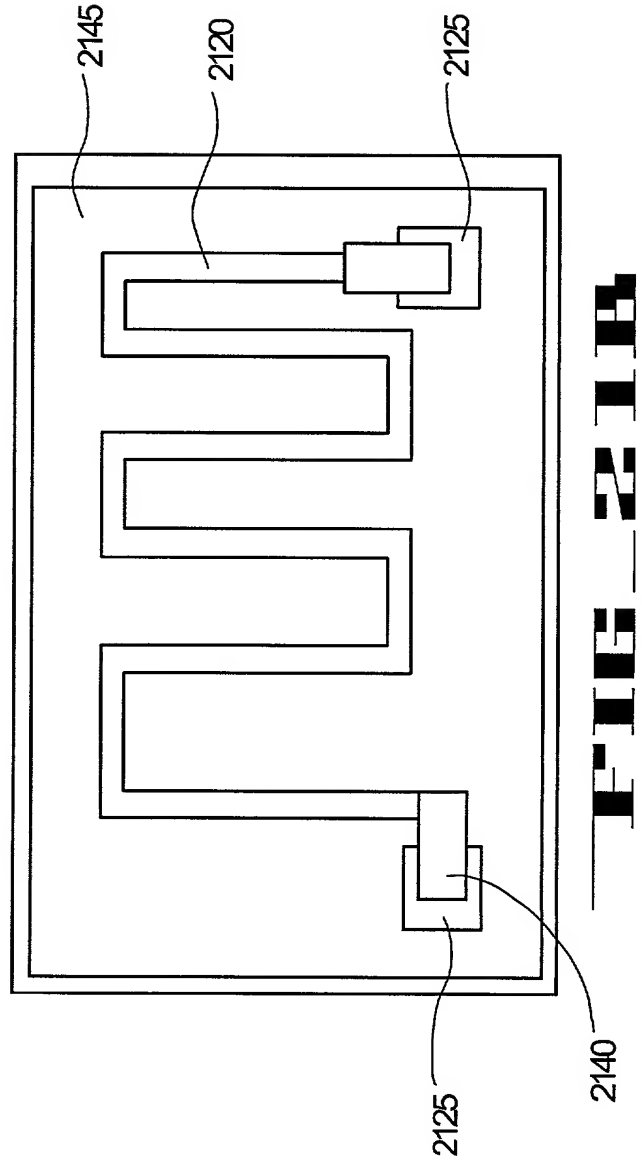


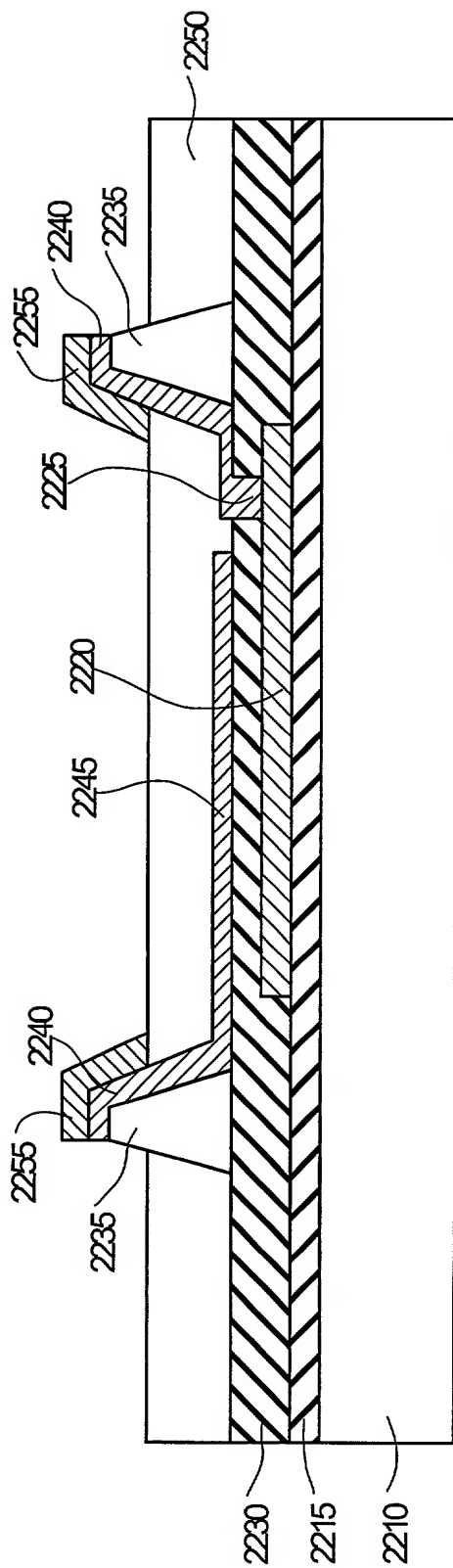
FIG. 20



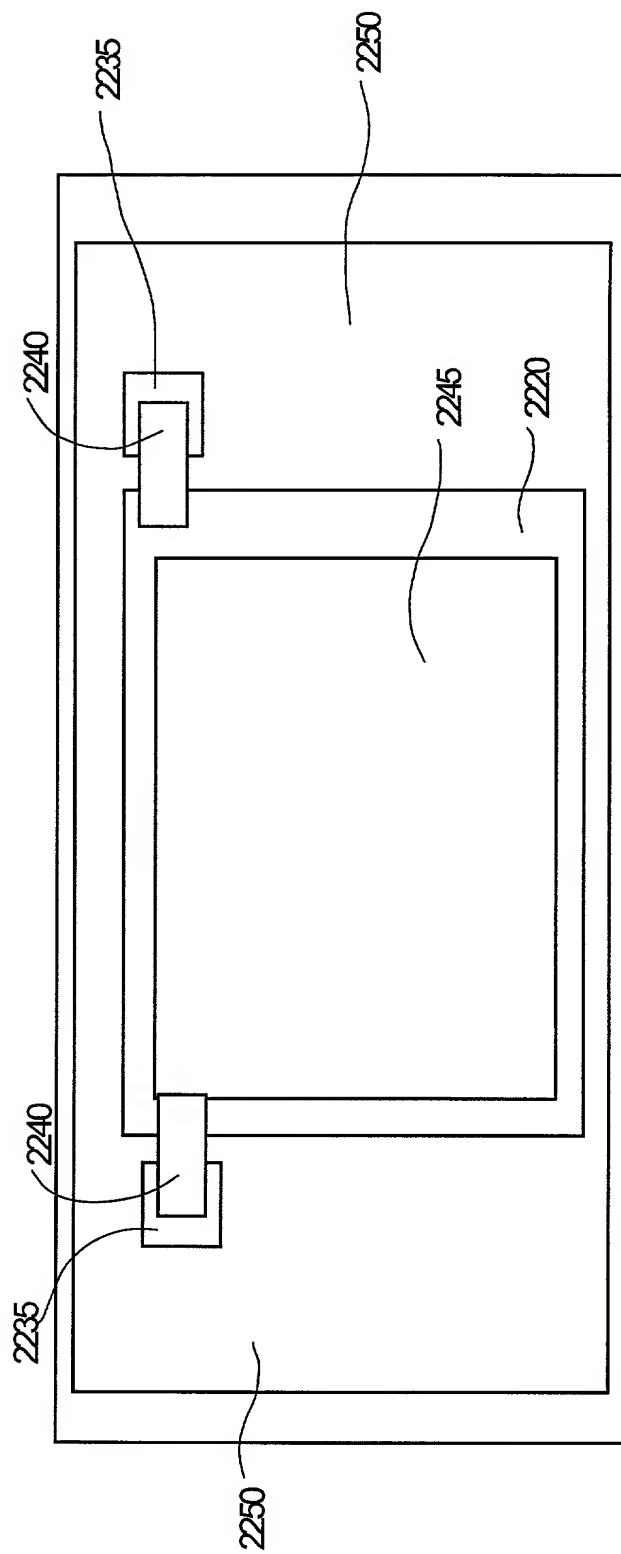
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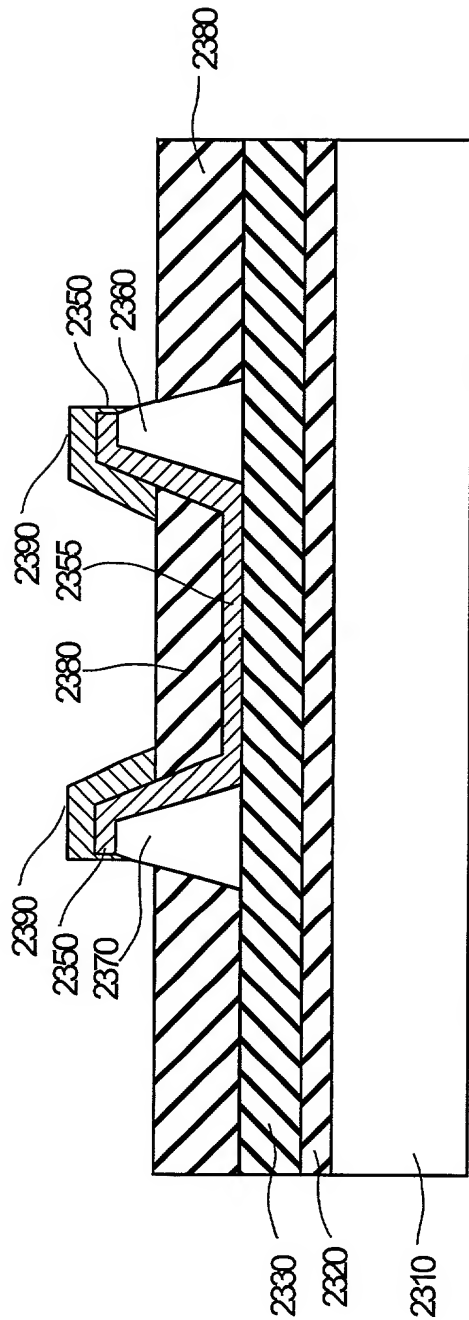


FIG. 23A

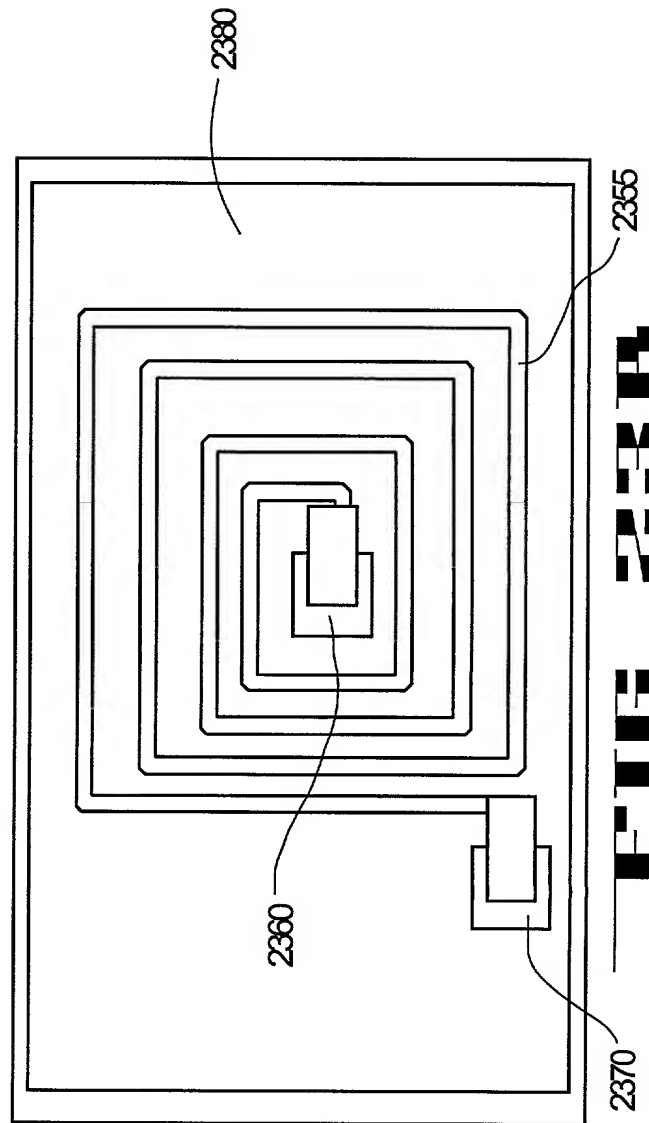


FIG. 23B

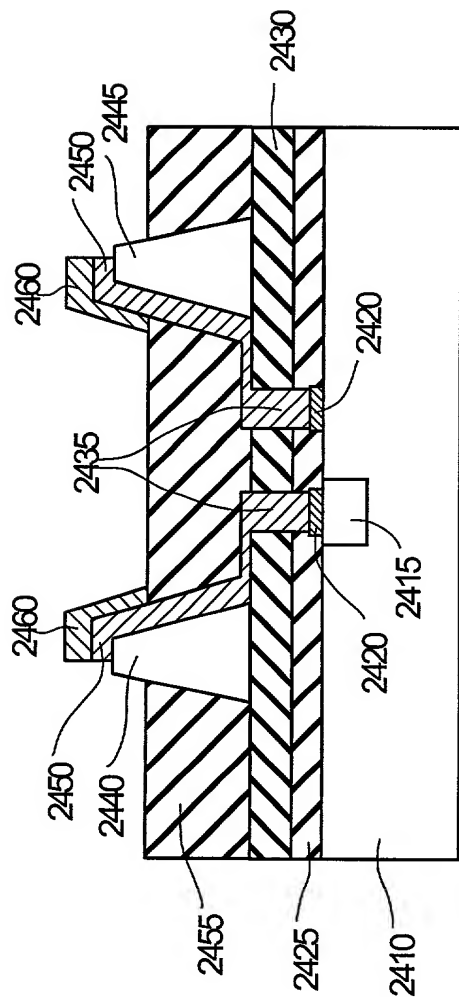


FIG. 24A

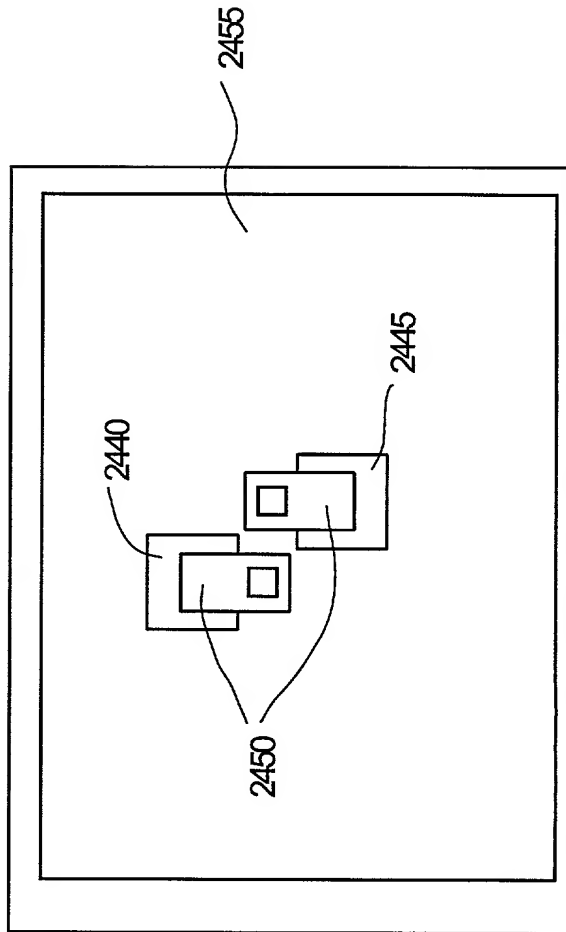


FIG. 24B